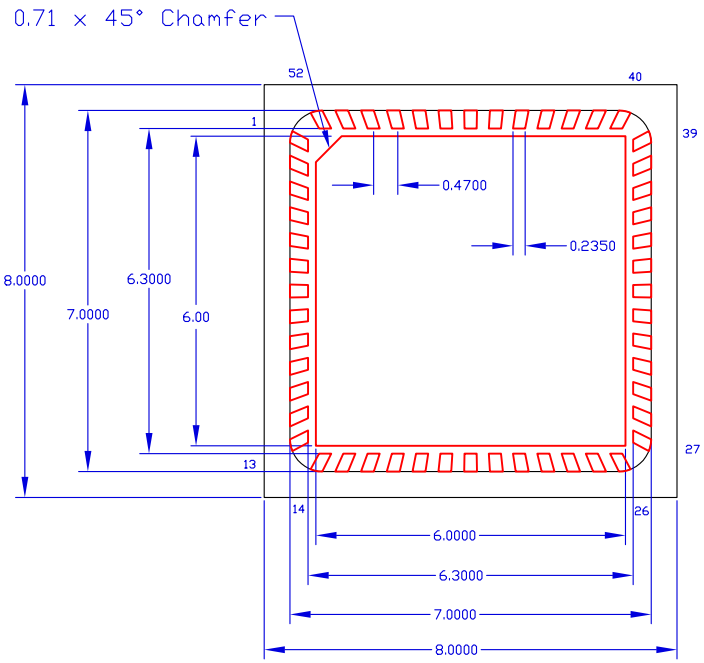
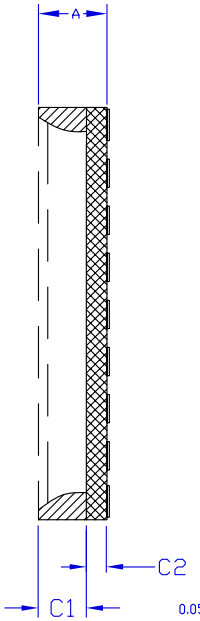
REV	DESCRIPTION	DATE	APPROVAL

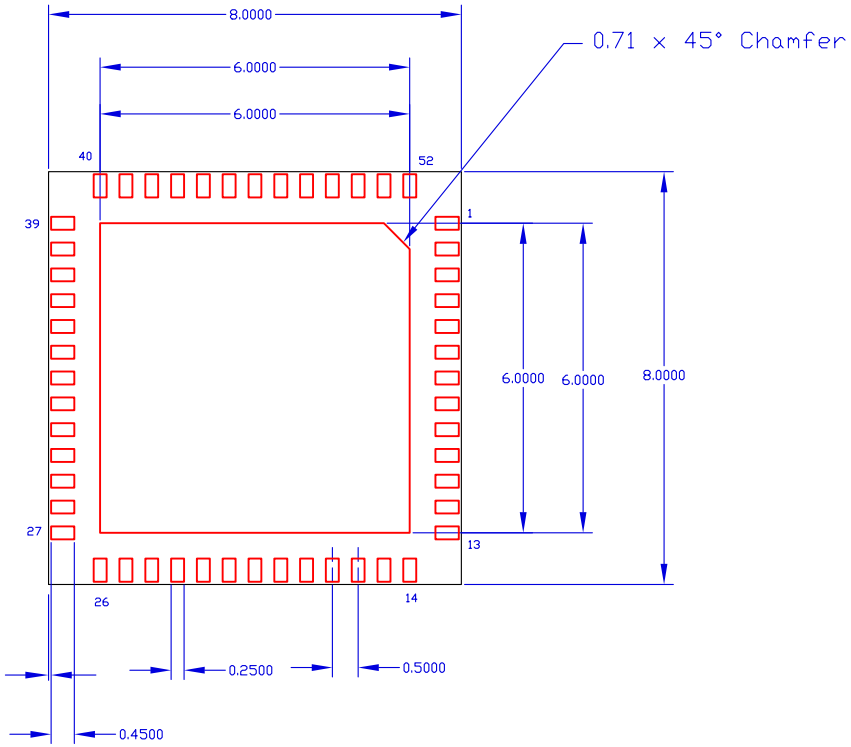
TOP VIEW

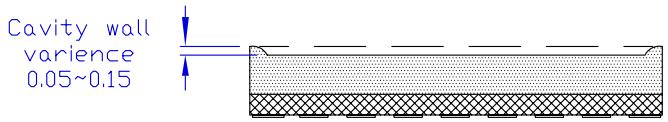


SIDE VIEW



BOTTOM VIEW





SIDE VIEW

Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12μm~18μm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3μm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13μm (5 micro-inch)
7. Nickel Thickness: 3.8μm (150 micro-inch)
8. All Dimensions Are mm

HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL +/-	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

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TOLERANCES UNLESS NOTED:	
X.XX	±
X.XXX	±
X.XXXX	±
ANGLES	±

ALL DIMENSIONS ARE IN: ☐ INCHES ☐ MILLIMETERS

THIRD ANGLE PROJECTION:

APPROVALS	DATE
DRAWN TA	11/29/08
ENG	
MFG	
QA	
CUST	
REVISED	

Mirror Semiconductor ™

TITLE 52-LEAD 8MM P=0.50MM A-QFN (AIR) OPEN CAVITY

SCALE	SIZE	DRAWING NO.	REV
NONE	A	455210	A

DO NOT SCALE DRAWING

SHEET 1 OF 1